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FIG.1A

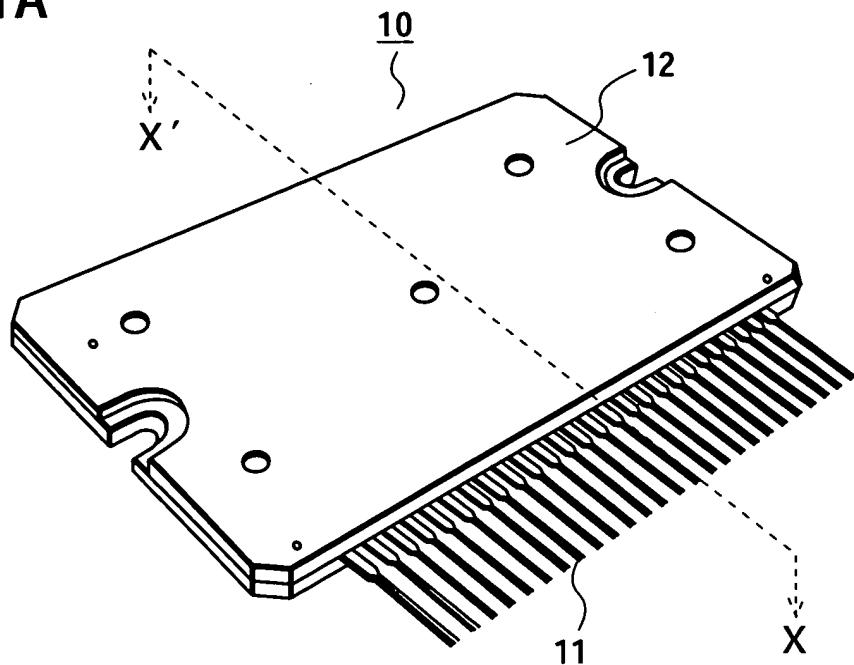
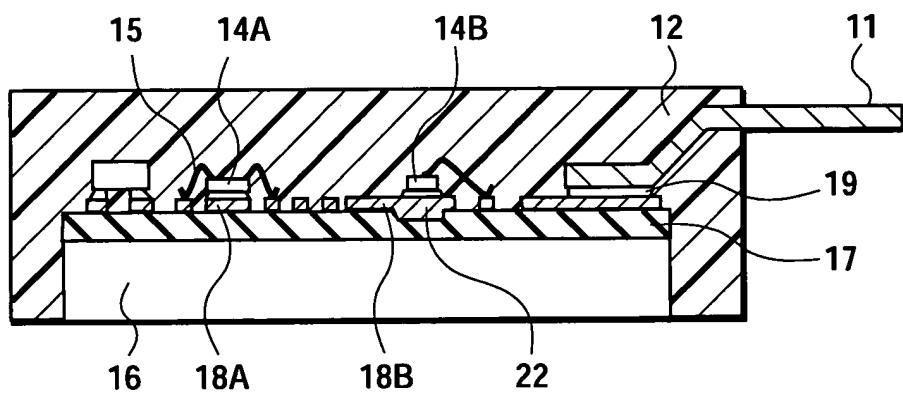
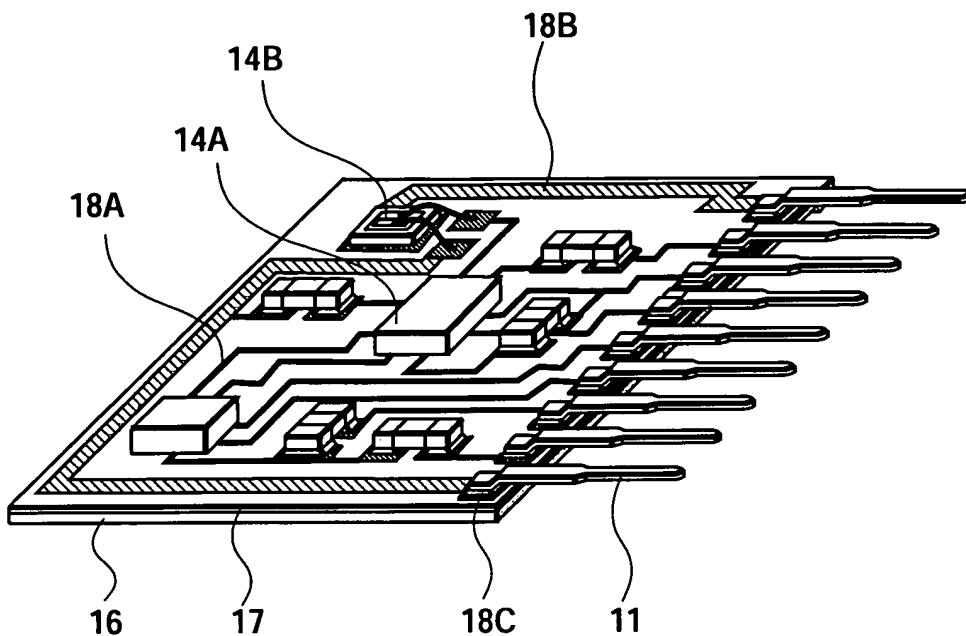


FIG.1B



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FIG.2

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FIG.3A

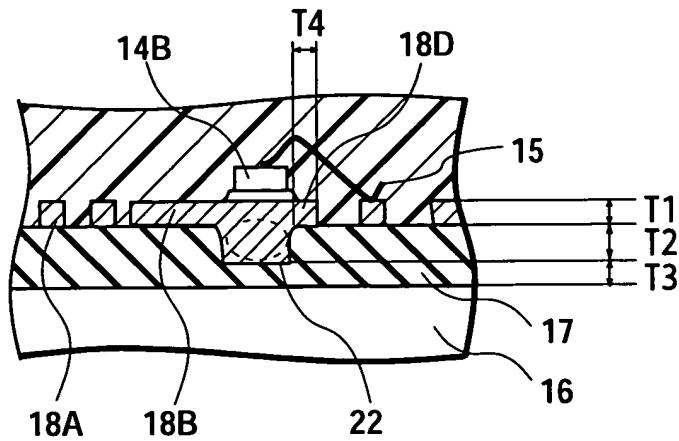


FIG.3B

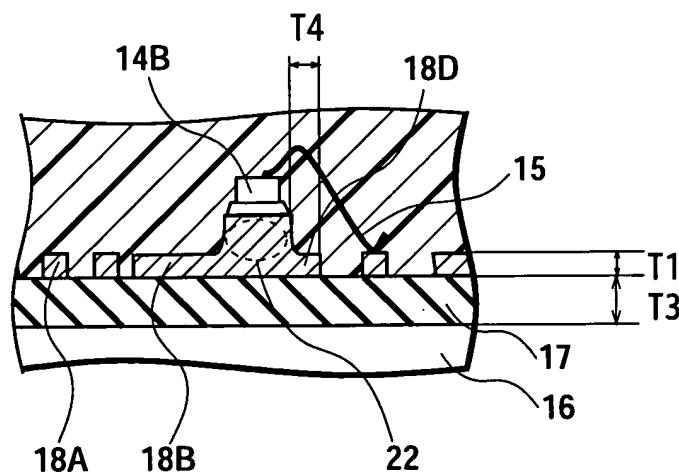
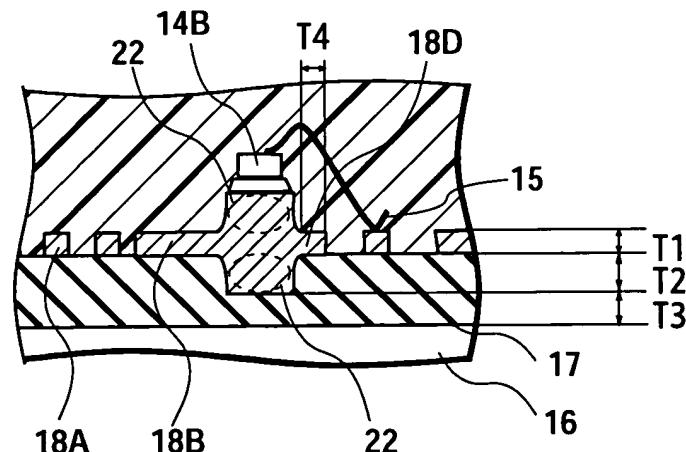
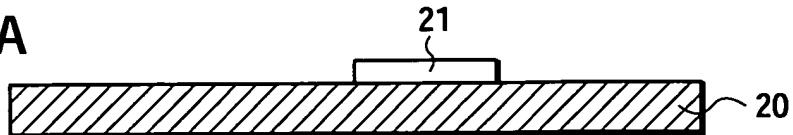
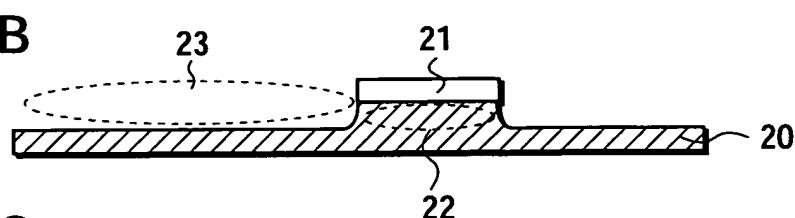
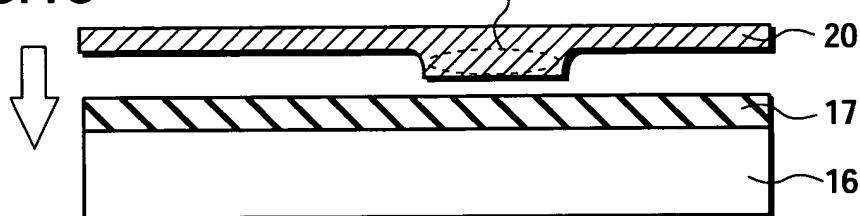
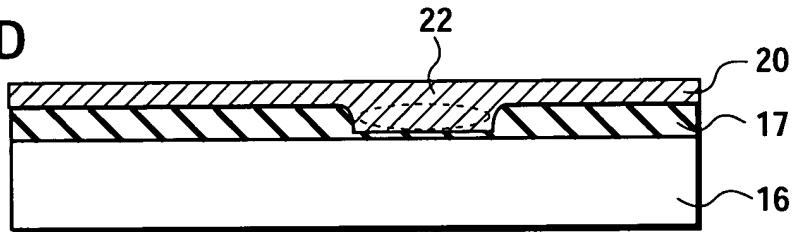
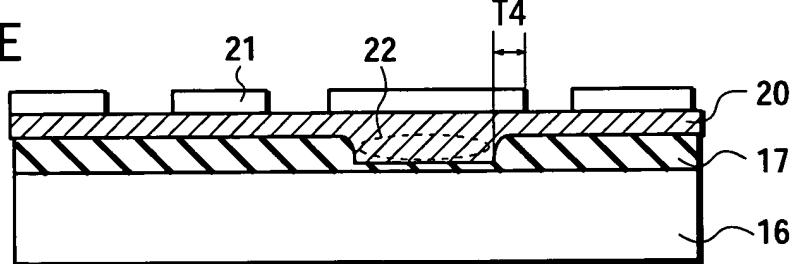
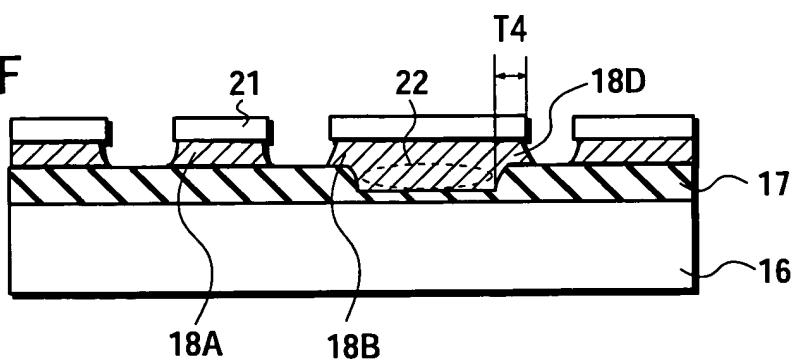


FIG.3C



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FIG.4A**FIG.4B****FIG.4C****FIG.4D****FIG.4E****FIG.4F**

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FIG.5A

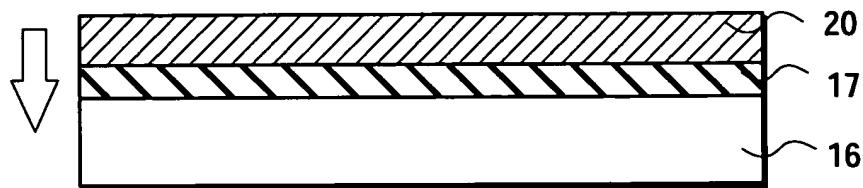


FIG.5B

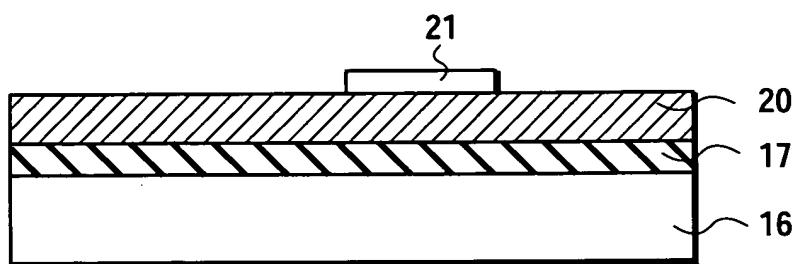


FIG.5C

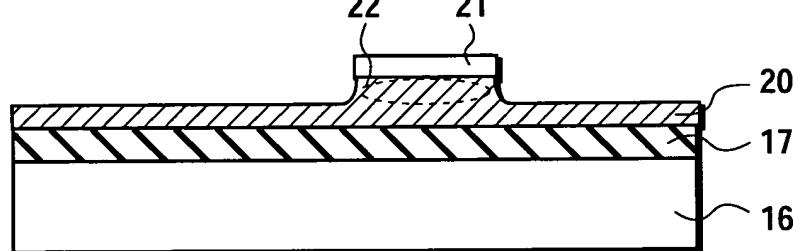


FIG.5D

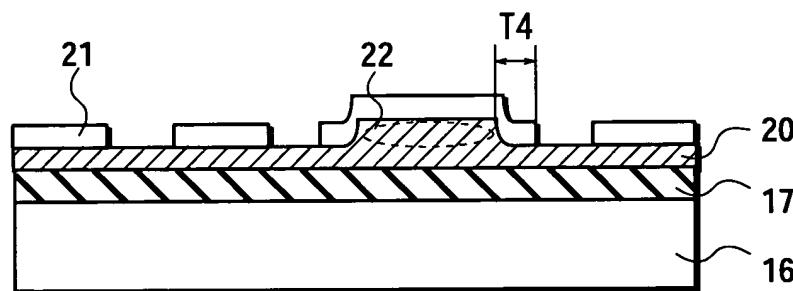
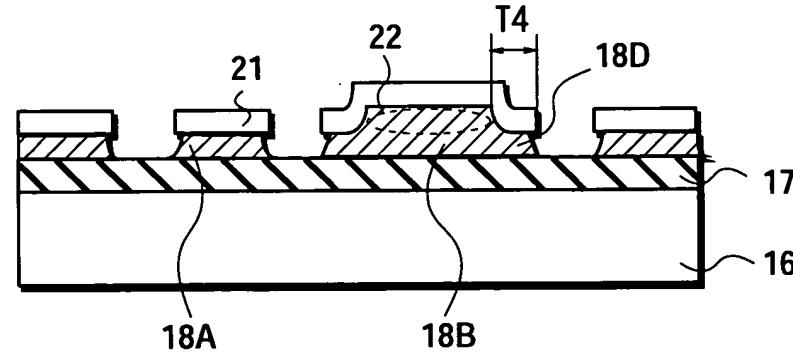


FIG.5E



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FIG.6A

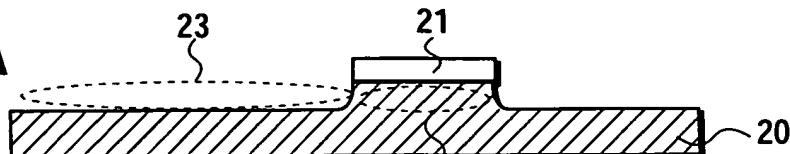


FIG.6B

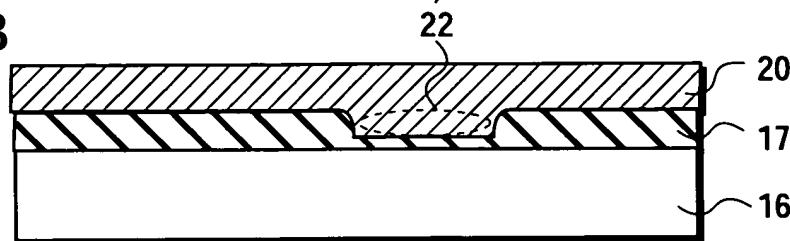


FIG.6C

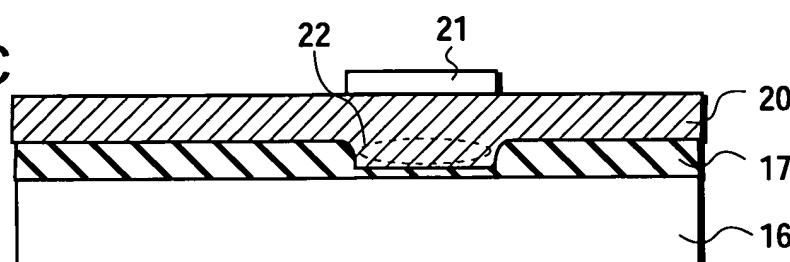


FIG.6D

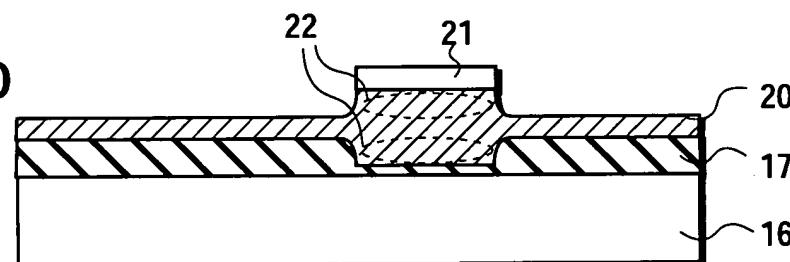


FIG.6E

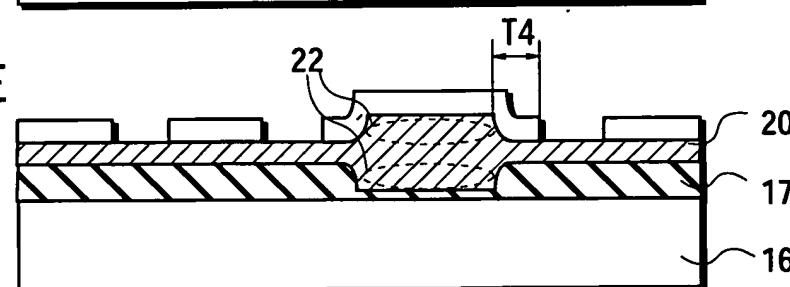
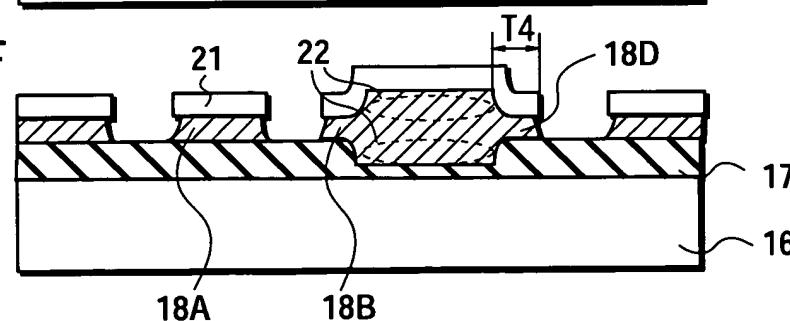


FIG.6F



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FIG.7A

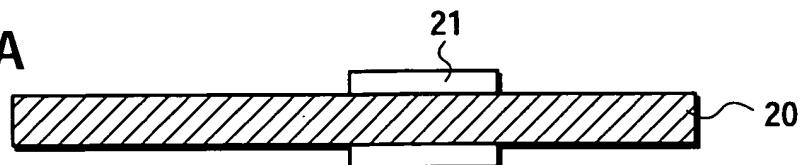


FIG.7B

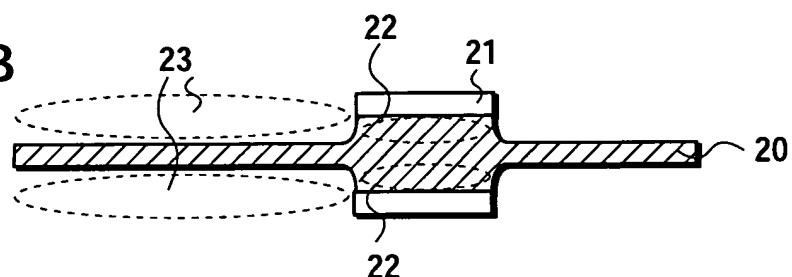


FIG.7C

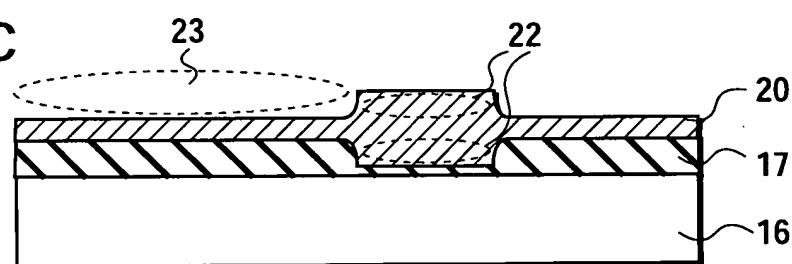


FIG.7D

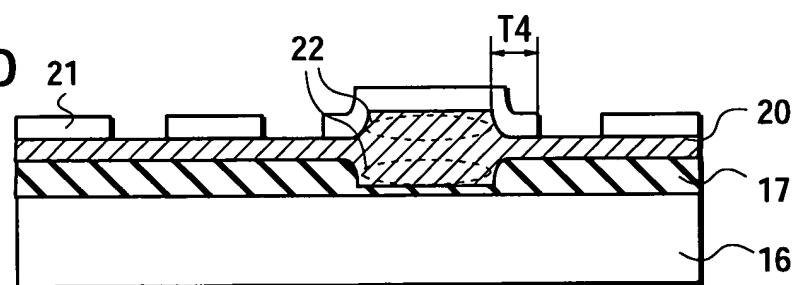
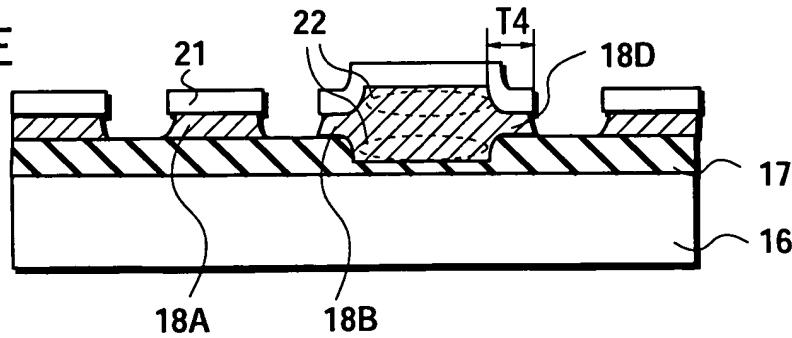
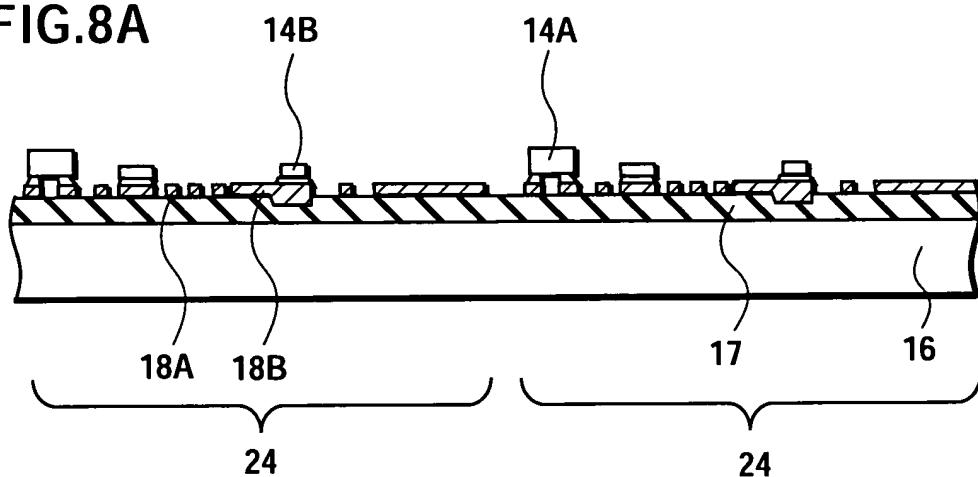
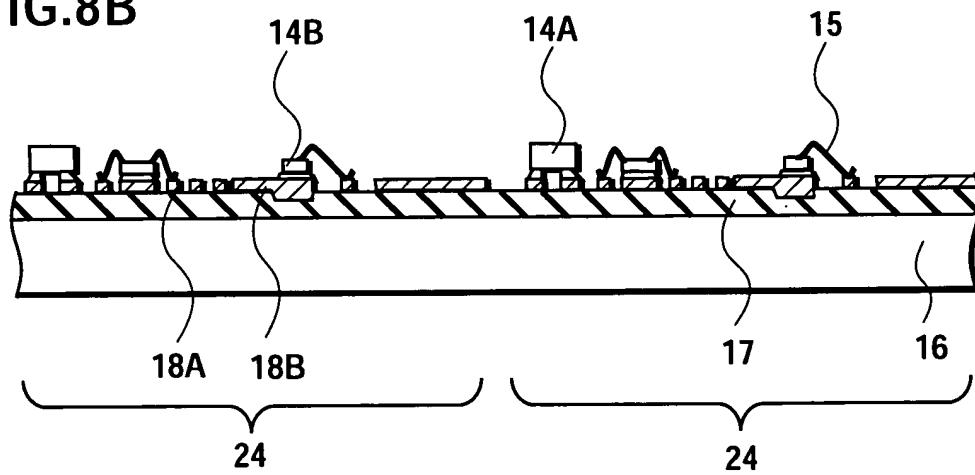


FIG.7E

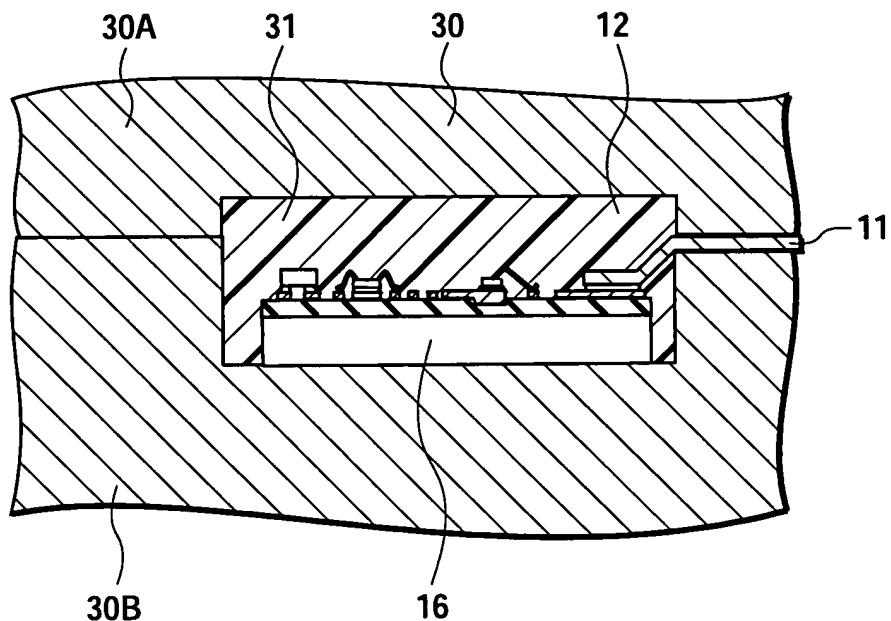


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FIG.8A**FIG.8B**

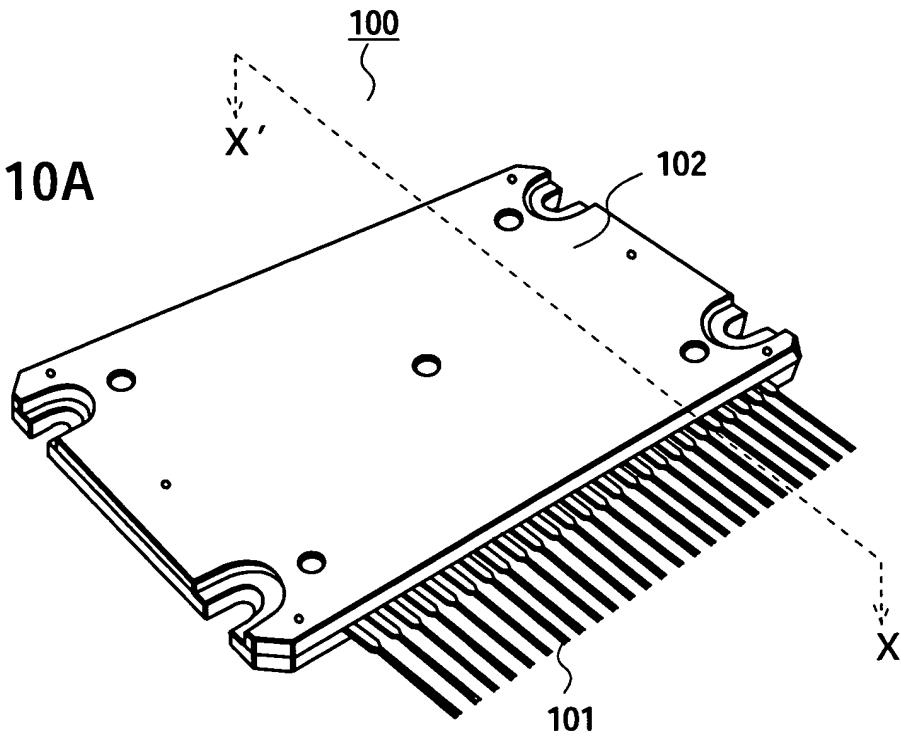
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FIG.9



Matter No.: 14225-111US1
F1040900US00
Applicant(s): Yusuke Igarashi et al.
CIRCUIT DEVICE AND METHOD OF MANUFACTURING THE
SAME

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FIG.10A**FIG.10B**